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BSI Standards Publication

Universal serial bus interfaces for data and power

Part 1-2: Common components — USB Power Delivery specification

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National foreword

This British Standard is the UK implementation of EN 62680-1-2:2022. It is identical to IEC 62680-1-2:2022. It supersedes BS EN IEC 62680-1-2:2021, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/100, Audio-visual equipment.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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© The British Standards Institution 2022
Published by BSI Standards Limited 2022

ISBN 978 0 539 20420 9

ICS 29.220; 33.120; 35.200

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This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 October 2022.

Amendments/corrigenda issued since publication

Date	Text affected
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EUROPÄISCHE NORM

October 2022

ICS 29.220; 33.120; 35.200

Supersedes EN IEC 62680-1-2:2021

English Version

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2022)

Interfaces de bus universel en série pour les données et
l'alimentation électrique - Partie 1-2: Composants communs
- Spécification de l'alimentation électrique par port USB
(IEC 62680-1-2:2022)

Schnittstellen des Universellen Seriellen Busses für Daten
und Energie - Teil 1-2: Gemeinsame Komponenten -
Festlegung für die USB-Stromversorgung
(IEC 62680-1-2:2022)

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The text of document 100/3716/CDV, future edition 6 of IEC 62680-1-2, prepared by IEC/TC 100 "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-2:2022.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2023-07-10
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2025-10-10

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –

Part 1-2: Common components – USB Power Delivery specification

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International Standard IEC 62680-1-2 has been prepared by technical area 18: Multimedia home systems and applications for end-user networks, of IEC technical committee 100: Audio, video and multimedia systems and equipment.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

Draft	Report on voting
100/3716/CDV	100/3763/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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A list of all parts in the IEC 62680 series, published under the general title *Universal serial bus interfaces for data and power*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication Universal Serial Bus Power Delivery Specification Revision 3.1, Version 1.1.

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**Universal Serial Bus
Power Delivery Specification**

Revision:* **3.1*

Version:* **1.1*

Release date:* **July 2021*

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Revision History

Revision	Version	Comments	Issue Date
1.0	1.0	Initial release Revision 1.0	5 July, 2012
1.0	1.1	Including errata through 31-October-2012	31 October 2012
1.0	1.2	Including errata through 26-June-2013	26 June, 2013
1.0	1.3	Including errata through 11-March-2014	11 March 2014
2.0	1.0	Initial release Revision 2.0	11 August 2014
2.0	1.1	Including errata through 7-May 2015	7 May 2015
2.0	1.2	Including errata through 25-March-2016	25 March 2016
2.0	1.3	Including errata through 11-January-2017	11 January 2017
3.0	1.0	Initial release Revision 3.0	11 December 2015
3.0	1.0a	Including errata through 25-March-2016	25 March 2016
3.0	1.1	Including errata through 12-January-2016	12 January 2017
3.0	1.2	Including errata through 21-June-2018	21 June 2018
3.0	2.0	Including errata through 29-August-2019	29 August 2019
3.1	1.0	Including errata through May 2021	May 2021
3.1	1.1	Including errata through July 2021	July 2021

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